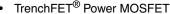


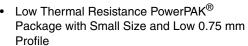
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P-Channel 20 V (D-S) MOSFET

PRODU	CT SUMMARY		
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I _D (A)	Q _g (Typ.)
	0.0036 at V _{GS} = - 10 V	- 40 ^e	
- 20	0.0048 at V _{GS} = - 4.5 V	- 40 ^e	72 nC
	0.0085 at $V_{GS} = -2.5 \text{ V}$	- 40 ^e	

FEATURES



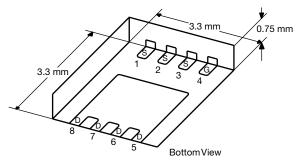




100 % R_g and UIS Tested

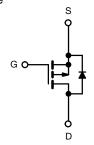
Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

PowerPAK 1212-8S



APPLICATIONS

- Smart Phones, Tablet PCs, Mobile Computing
 - Battery Switch
 - Load Switch



P-Channel MOSFET

Ordering Information: Si7655DN-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	- 20	V
Gate-Source Voltage		V _{GS}	± 12	
	T _C = 25 °C		- 40 ^e	
Continuous Drain Current (T = 150 °C)	T _C = 70 °C	1 .	- 40 ^e	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	- 31 ^{a, b}	
	T _A = 70 °C		- 25 ^{a, b}	
Pulsed Drain Current (t = 300 μs)		I _{DM}	- 100	Α
Continuous Courses Dunie Diodo Coursest	T _C = 25 °C	I.	- 40 ^e	
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	- 4 ^{a, b}	
Avalanche Current	T _A = 25 °C	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 IIII1	E _{AS}	20	mJ
	T _C = 25 °C		57	
Maximum Dawar Dissination	T _C = 70 °C	P _D	36	w
Maximum Power Dissipation	T _A = 25 °C	' b	4.8 ^{a, b}	VV
	T _A = 70 °C	1	3 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 50 to 150	°C
Soldering Recommendations (Peak Temperature) ^{c, d}			260	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s
- c. See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- e. Package limited.

Document Number: 63617 S12-2393-Rev. B, 15-Oct-12 For technical questions, contact: pmostechsupport@vishay.com

Si7655DN

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THERMAL RESISTANCE RATIN	IGS				
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	21	26	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.7	2.2	C/ VV

Notes:

a.Surface mounted on 1" x 1" FR4 board. b.Maximum under steady state conditions is 63 °C/W

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static	2,	1 100 000000		- 3 %		3
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J			- 12		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.6		°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.5		- 1.1	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
Zana Oata Vallana Busin Oamant		V _{DS} = - 20 V, V _{GS} = 0 V			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α
	5(611)	V _{GS} = - 10 V, I _D = - 20 A		0.0030	0.0036	V mV/ °C V nA μA A 6 8 Ω Ω 5 S PF nC Ω Ω ns
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 15 A		0.0039	0.0048	
	23(3)	V _{GS} = - 2.5 V, I _D = - 10 A		0.0062	0.0085	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 20 A		90		S
Dynamic ^b	- 12					
Input Capacitance	C _{iss}			6600		
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		890		рF
Reverse Transfer Capacitance	C _{rss}			930		
Total Cata Charge		V _{DS} = - 10 V, V _{GS} = - 10 V, I _D = - 20 A		150	225	
Total Gate Charge	Q_g			72	110	
Gate-Source Charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -20 \text{ A}$		12		nc
Gate-Drain Charge	Q _{gd}			19		
Gate Resistance	R_{g}	f = 1 MHz	0.5	2.6	5.2	Ω
Turn-On Delay Time	t _{d(on)}			45	90	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 1 \Omega$		45	90	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		100	200	
Fall Time	t _f			35	70	
Turn-On Delay Time	t _{d(on)}			13	25	ns
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 1 \Omega$		10	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		110	220	
Fall Time	t _f			25	50	
Drain-Source Body Diode Characterist	ics					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 40 ^c	۸
Pulse Diode Forward Current ^a	I _{SM}				- 100	А
Body Diode Voltage	V _{SD}	I _F = - 10 A		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns
Body Diode Reverse Recovery Charge	Q _{rr}	1 10 A dl/dt 100 A/:- T 05 00		17	26	nC
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		15		ns
Reverse Recovery Rise Time	t _b	1		15		

Notes:

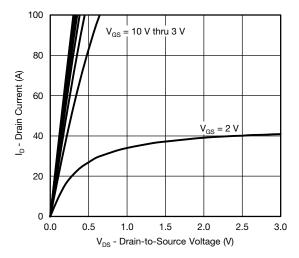
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Package limited.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

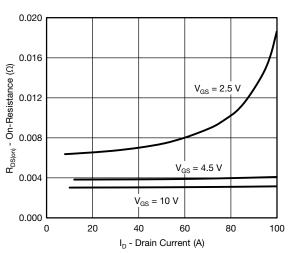


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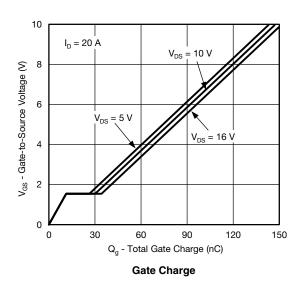
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

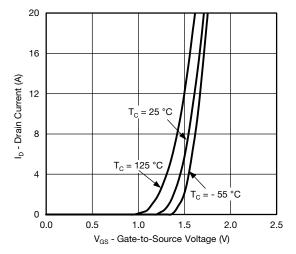


Output Characteristics

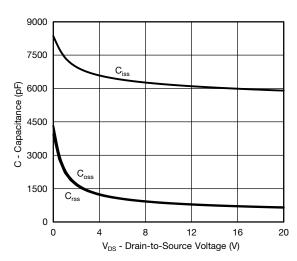


On-Resistance vs. Drain Current and Gate Voltage

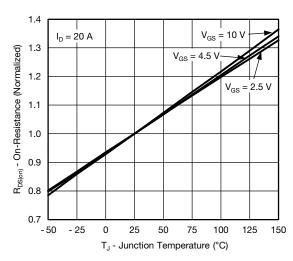




Transfer Characteristics



Capacitance

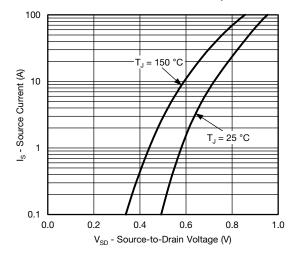


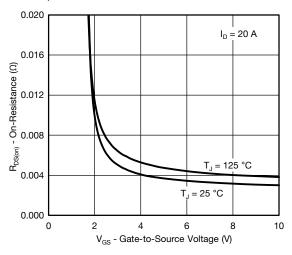
On-Resistance vs. Junction Temperature

Si7655DN

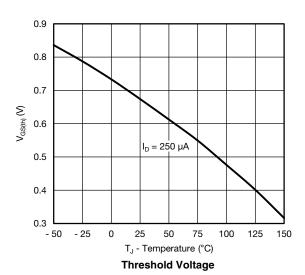
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

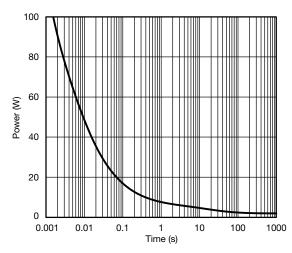




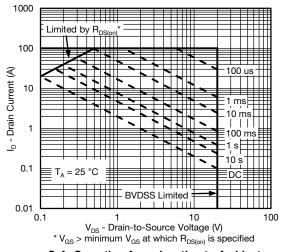
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

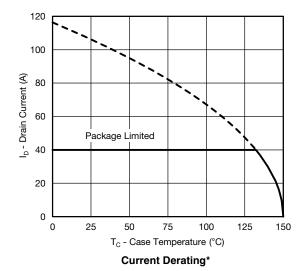


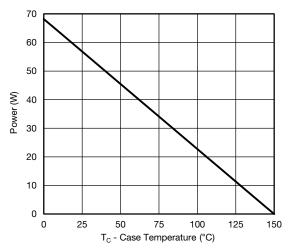
Safe Operating Area, Junction-to-Ambient



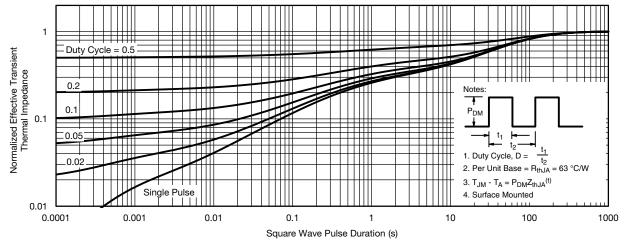
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Power, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient

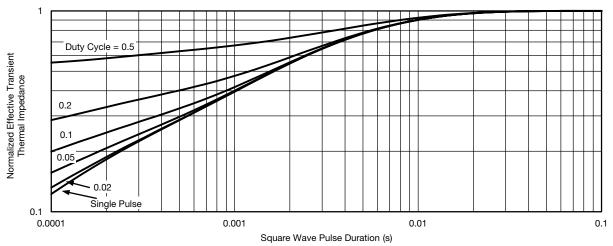
 $^{^*}$ The power dissipation P_D is based on $T_{J(max)}$ = 150 $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

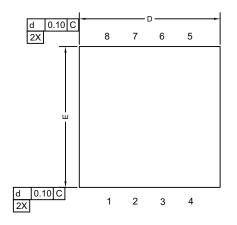


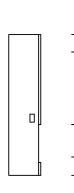
Normalized Thermal Transient Impedance, Junction-to-Case

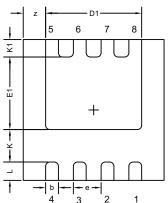
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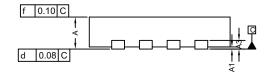


Case Outline for PowerPAK® 1212-8S









DIM.	MILLIMETERS			INCHES				
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	0.67	0.75	0.83	0.027	0.030	0.033		
A1	0	-	0.05	0	-	0.002		
А3		0.20 REF			0.008 REF			
b	0.30 BSC			0.012 BSC				
D	3.30 BSC 0.130 BSC							
D1	2.15	2.25	2.35	0.084	0.088	0.092		
E		3.30 BSC			0.130 BSC			
E1	1.60	1.70	1.80	0.063	0.067	0.071		
е		0.65 BSC			0.026 BSC			
K		0.76 TYP		0.030 TYP				
K1		0.41 TYP		0.016 TYP				
L	0.43 BSC			0.017 BSC				
Z		0.525 TYP		0.021 TYP				

DWG: 6008

Note

• Millimeters will govern.



RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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